PRODUCT CHANGE NOTICE

Refer to:
PCN00061

Date: 7/19/00

Intersil Agreement with ChipPAC

- **Intersil Completes Multi-year Supply Agreement With ChipPAC**
- **Sale of Kuala Lumpur, Malaysia Based Semiconductor Assembly and Test Operations to ChipPAC**

July 19, 2000

To: Our Valued Intersil Customers

Subject: **Notice of Intersil Agreement with ChipPAC**

- **Completion of a Multi-year Supply Agreement With ChipPAC**
- **Sale of Intersil's Kuala Lumpur, Malaysia Based Semiconductor Assembly and Test Operations to ChipPAC**

This letter will inform you that Intersil has entered into a multi-year supply agreement for assembly, test and product distribution services with ChipPAC, Inc. of Santa Clara, California. Under terms of this agreement, Intersil has sold our Kuala Lumpur, Malaysia based semiconductor assembly and test operations to ChipPAC, who will supply services on a subcontract basis.

This agreement provides Intersil with the opportunity to increase concentration on design, development, and customer service. It affords Intersil additional test capacity and access to new packaging technologies. ChipPAC is one of the world's largest providers of semiconductor packaging and test services. The company, which has an impressive customer list, offers a wide array of packaging, from basic 6-pin to 2000-pin BGA/CSP and leaded packages. ChipPAC's manufacturing facilities, located in Ichon, Korea, Shanghai, China and Kuala Lumpur, Malaysia are ISO9000, QS9000 and ISO14001 certified. Intersil plans to qualify the ChipPAC Shanghi and Ichon facilities as additional assembly sites for selected products over the next few months.

The Kuala Lumpur, Malaysia facility will maintain systems compliant to MIL-PRF-19500 and MIL-PRF-38535. In addition, they will maintain certification to MIL-PRF-19500.

Specifics of site qualification dates and plans are being formulated as applicable. Customers will be issued a formal change notice with more specific information, including part types and projected dates for site qualifications.

It is targeted that thirty days after completion of each site qualification, Intersil will have the option to implement processing at the new site. Customers with specific qualification requirements, previously negotiated with and accepted by Intersil, may be contacted prior to the initiation of qualification plans and the start of qualifications to discuss qualification requirements and implementation plans.

Customers may be sure that Intersil will take all necessary actions to conform to customer requirements and to ensure the continued high quality and reliability of Intersil products. We anticipate a smooth transition as many of the current ChipPAC employees were previously trained to and have experience with Intersil's procedures and customer requirements.

Please contact your Regional Sales Office if you wish additional information at this time. If you prefer, you may contact our Intersil Hot Line, at 1-888-468-3774, if in the United States or 1-321-724-7143 if outside the United States.

Joan C. Sherman
Intersil Corporation

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